

## C0805X132K2TACTU

Aliases (C0805X132K2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 1,300 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm

Packaging

Packaging Quantity

-	211111 1/ 0.5111111	Micus
W	1.25mm +/-0.3mm	Tolera
Т	0.78mm +/-0.20mm	Volta
S	0.6mm MIN	Diele
В	0.5mm +/-0.25mm	Temp
		Temp
Packaging Specifications		Capa

4000

T&R, 180mm, Plastic Tape

Specifications		
Capacitance	1,300 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	10%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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